

## Features

- Glass passivated chip
- Super fast switching for high efficiency
- For surface mounted applications
- Low forward voltage drop and high current capability
- Low reverse leakage current
- Plastic material has UL flammability classification 94V-0



DO-214AA (SMB)

## Absolute Maximum Ratings ( $T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	ES3 AB	ES3 BB	ES3 CB	ES3 DB	ES3 FB	ES3 GB	ES3 JB	ES3 KB	ES3 MB	Unit
Maximum Repetitive Peak Reverse Voltage	$V_{RRM}$	50	100	150	200	300	400	600	800	1000	V
Maximum RMS Voltage	$V_{RMS}$	35	70	105	140	210	280	420	560	700	V
Maximum DC Blocking Voltage	$V_{DC}$	50	100	150	200	300	400	600	800	1000	V
Maximum Average Forward Rectified Current ( $T_L=100^\circ\text{C}$ )	$I_{F(AV)}$	3.0								A	
Peak Forward Surge Current 8.3 ms Single Half Sine-wave Superimposed on Rated Load	$I_{FSM}$	100								A	
Operating Junction Temperature Range	$T_J$	-55 to +150								$^\circ\text{C}$	
Storage Temperature Range	$T_{STG}$	-55 to +150								$^\circ\text{C}$	

## Electrical Characteristics ( $T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	ES3 AB	ES3 BB	ES3 CB	ES3 DB	ES3 FB	ES3 GB	ES3 JB	ES3 KB	ES3 MB	Unit				
Maximum Instantaneous Forward Voltage @3.0A DC	$V_F$	0.92				1.25		1.7		V					
Typical Junction Capacitance <sup>2</sup>	$C_J$	45								pF					
Maximum DC Reverse Current at Rated DC Blocking Voltage	$I_R (T_J=25^\circ\text{C})$	10								uA					
	$I_R (T_J=125^\circ\text{C})$	500								uA					
Typical Reverse Recovery Time <sup>1</sup>	$t_{rr}$	35								nS					
Typical Thermal Resistance Junction to Ambient <sup>4</sup>	$R_{\theta JA}$	50								$^\circ\text{C/W}$					
Typical Thermal Resistance Junction to Lead <sup>3</sup>	$R_{\theta JL}$	10								$^\circ\text{C/W}$					

- Notes:**
1. Reverse Recovery Test Conditions:  $I_F=0.5\text{A}$ ,  $I_R=1.0\text{A}$ ,  $I_{RR}=0.25\text{A}$
  2. Measured at 1 MHz and Applied  $V_R=4.0$  Volts
  3. Thermal Resistance junction to Lead.
  4. Thermal Resistance junction to Ambient.

## Typical Characteristics Curves

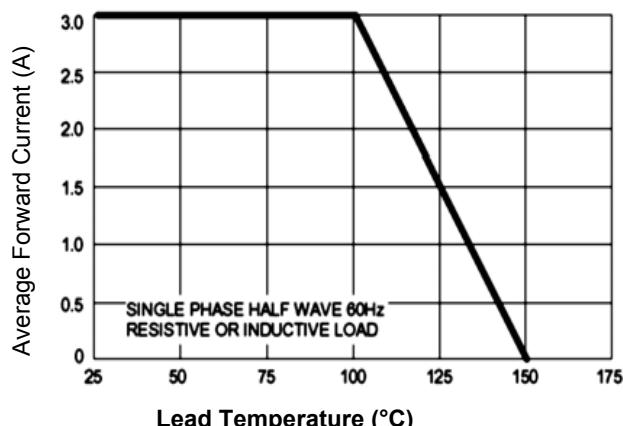


Figure 1. Forward Current Derating Curve

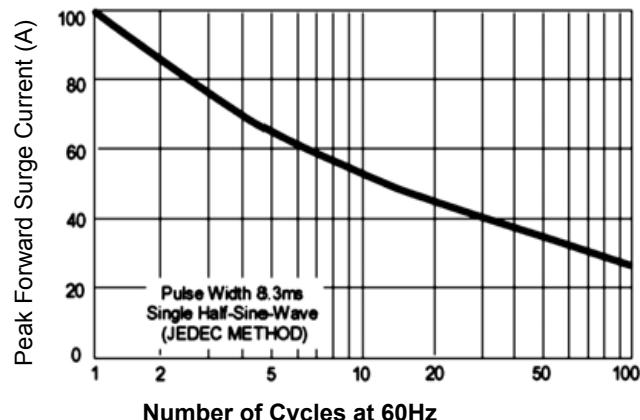


Figure 2. Maximum Non-Repetitive Surge Current

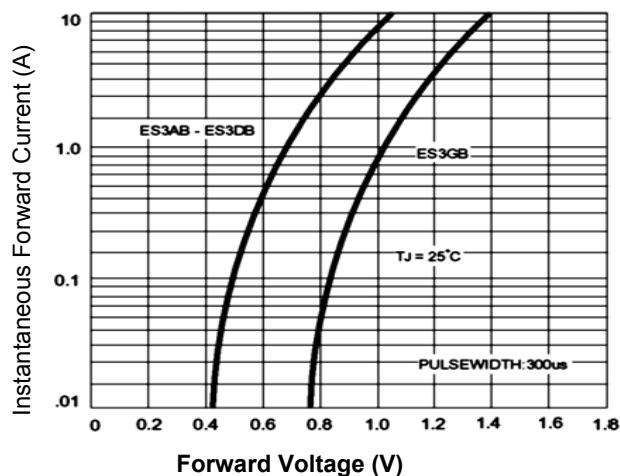


Figure 3. Typical Forward Characteristics

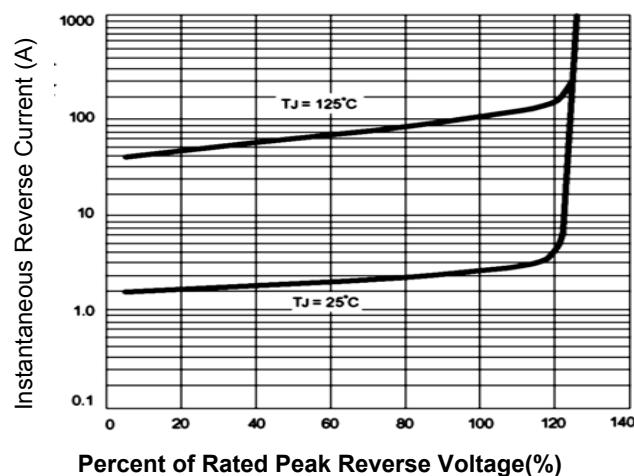
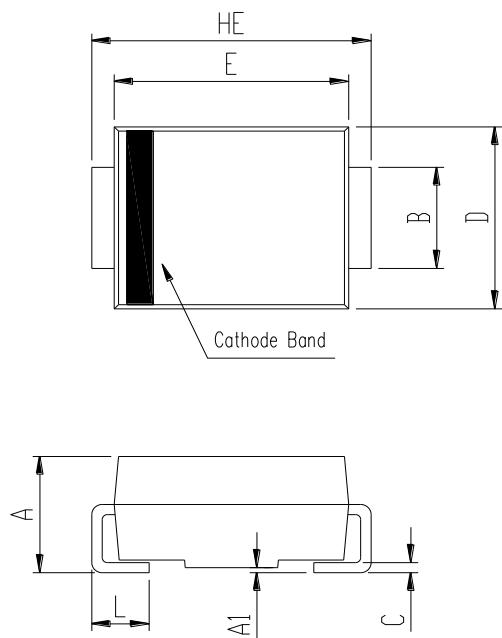


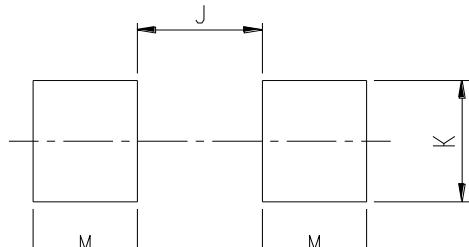
Figure 4. Typical Reverse Characteristics

## Package Outline Dimensions DO-214AA (SMB)



SMB (DO-214AA)				
DIM	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	1.99	2.61	0.078	0.103
A1	0.00	0.20	0.000	0.008
B	1.93	2.08	0.076	0.082
C	0.15	0.31	0.006	0.012
D	3.48	3.73	0.137	0.147
E	4.25	4.75	0.167	0.187
HE	5.26	5.46	0.207	0.215
L	0.90	1.41	0.035	0.056

## Recommended Pad Layout



SMB Recommended Pad Layout (Reference Only)				
DIM	Millimeters		Inches	
	Min.	Max.	Min.	Max.
J	-	2.60	-	0.102
K	2.20	-	0.087	-
M	1.80	-	0.071	-